

CupraEtch® SR 8000

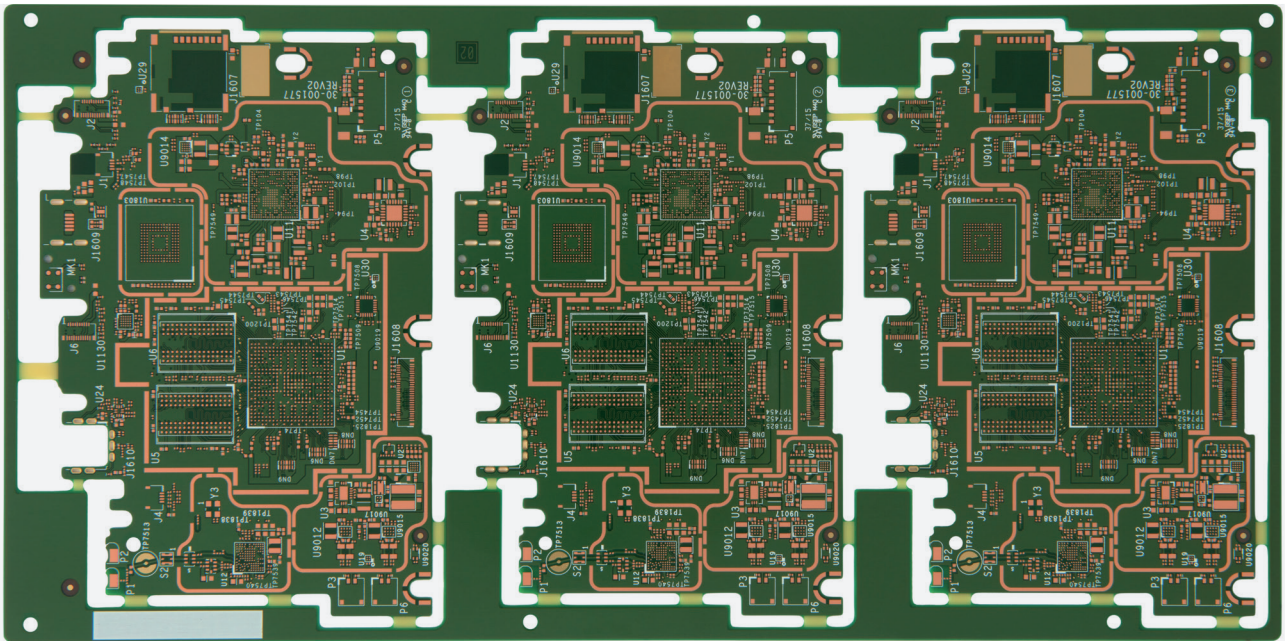
Advanced surface preparation



Electronics

Surface treatment technology

atotech.com



Advanced pretreatment for dryfilm and soldermask adhesion



Metal complex free solution

Excellent dryfilm and soldermask adhesion

CupraEtch® SR 8000 is a cupric chloride based microetching system with unique additives. The simple three step process creates uniform roughening of surface at low temperatures. Atotech's cost-effective pretreatment easily drops into existing lines and reliably improves the adhesion of all copper types to industry standard dryfilm and soldermask types. The metal complex-free solution leads to cost-effective waste water treatment.

Features and benefits

- Fulfills demanding automotive OEM requirements
- Successfully passes advanced HDI requirements ($< 30 \mu\text{m L/S}$) with superior dryfilm adhesion
- Creates sufficient roughness for excellent adhesion on soldermask at low etch depths
- Excellent compatibility to wide range of selective finish processes

High adhesion performance with minimum etch depth for cost effectiveness

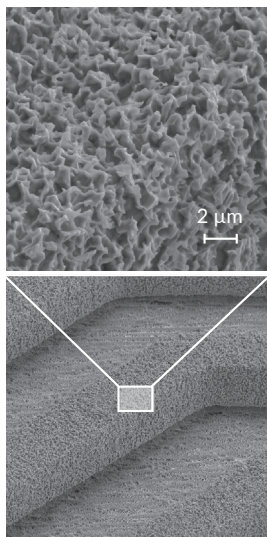


Figure 1:
Street view of fine line treated
with CupraEtch® SR 8000

Easy process implementation with excellent stability

- Drop-in solution to existing surface preparation line
- Simple analysis methods for easy handling and process control

	Cut board 0 m ²	Cut board 500 m ²	Cut board 1000 m ²	Cut board 1500 m ²	Cut board 2000 m ²	Cut board 2500 m ²
cosmetic						
SEM mag 5k						

Production benefits by using CupraEtch® SR 8000

- Consistent and reliable performance for dryfilm and soldermask adhesion
- Reduced make-up frequency due to high copper loading
- Suitable for a wide range of copper types including CCL, DC and pulse plated panels
- Simplified waste water treatment due to zero complexing agents

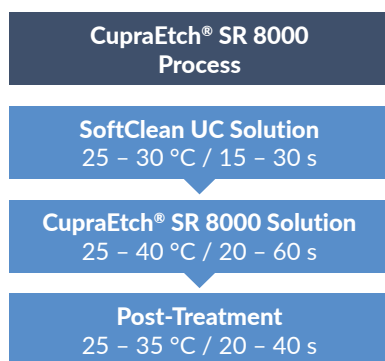


Figure 2: CupraEtch® SR 8000 process
sequence

